



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Smith et al.

Docket No.: TI-29811

Serial No.: 09/975,639

Art Unit: 2818

Filed: 10/11/01

Examiner: Hoang, Quoc

Title: Hydrogen Plasma Photoresist Strip And Polymeric Residue Cleanup Process  
For Low Dielectric Constant Materials

TECHNOLOGICAL CENTER 2800

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marsha  
4/18/02

AMENDMENT UNDER 37 CFR 1.111

June 6, 2002

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited  
with the U.S. Postal Service on  
6-6-03 as First Class Mail in an  
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Karen Vertz 6-6-03  
Karen Vertz Date

In response to the Office Action, dated 03/14/03, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.